



Final Product/Process Change Notification

Document # : FPCN20349XC

Issue Date: 28 August 2017

Title of Change:	Qualification of Niigata Fab (Japan) as the additional wafer source for Bipolar Power Planar Transistors.		
Proposed first ship date:	5 December 2017 or earlier upon customer approval		
Contact information:	Contact your local ON Semiconductor Sales Office or < Hiroshi.Koizumi@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Hiroshi.Koizumi@onsemi.com>.		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.		
Change Part Identification:	Affected products will be identified with date code.		
Change category:	☒ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other _____		
Change Sub-Category(s):	☒ Manufacturing Site Change/Addition ☐ Manufacturing Process Change ☐ Material Change ☐ Product specific change ☐ Datasheet/Product Doc change ☐ Shipping/Packaging/Marking ☐ Other: _____		
Sites Affected:	☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : ON Niigata, Japan ☐ External Foundry/Subcon site(s)		
Description and Purpose:			
This is the Final Notification by ON Semiconductor notifying customers of its plan to add Niigata Fab (Japan) as the qualified wafer source for Bipolar Power Planar Transistor. The Niigata Fab facility is an ON Semiconductor owned wafer fab that has been producing products for ON Semiconductor. Several existing technologies within ON Semiconductor's product families are currently sourced from Niigata Fab. ON Semiconductor Niigata Wafer Fab is an internal factory that is TS16949, ISO-9001 and ISO-14000 certified. Qualification tests are designed to show that the reliability of the impacted devices will continue to meet or exceed ON Semiconductor standards			

**Reliability Data Summary:**QV DEVICE NAME MJE5852GRMS: 23106PACKAGE: TO220

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1008 hrs	0/80
Autoclave	JESD22-A102	Ta=121°C, RH=100% 15psig	96 hrs	0/80
H3TRB	JESD22-A101	Ta= 85°C, 85% RH, 80%bias	1008 hrs	0/80
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 3.5 min	8572 cyc	0/80
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/80
RSH	JESD22- B106	Ta = 260C, 10 sec		0/30

QV DEVICE NAME MJD340T4GRMS: 23107PACKAGE: DPAK

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1008 hrs	0/160
Autoclave+PC	JESD22-A102	Ta=121°C, RH=100% 15psig	96 hrs	0/160
H3TRB+PC	JESD22-A101	Ta= 85°C, 85% RH, 80%bias	504 hrs	0/160
IOL+PC	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	7500 cyc	0/160
TC+PC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/160
RSH	JESD22- B106	Ta = 260C, 10 sec		0/60

QV DEVICE NAME NJW0281GRMS: 34697PACKAGE: TO-3P

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1008 hrs	0/80
H3TRB	JESD22-A101	Ta= 85°C, 85% RH, 80%bias	1008 hrs	0/80
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	6000 cyc	0/80
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/80

Electrical Characteristic Summary:

Electrical characteristics are not impacted.



List of affected Standard Parts:

Part Number	Qualification Vehicle
MJD210G	MJD340T4G/MJE5852G
MJD210RLG	
MJD210T4G	
MJD253-1G	
MJD253T4G	
MJD350T4G	
MJD5731T4G	
MJE15035G	
MJE210G	
MJE253G	
MJE5730G	
MJE5731AG	
MJE5731G	
MMJT350T1G	
NJD1718T4G	
2N6338G	NJW0281G
2N6341G	
BUV26G	
BUV27G	
MJD200G	
MJD200RLG	
MJD200T4G	
MJD243G	
MJD243T4G	
MJD44E3T4G	
MJE200G	
MJE243G	
MJE270G	
NJW44H11G	
NJL0281DG	